

Wire Wound Chip Ferrite Inductors size 0805

◆Feature

Minature Size.smallchipsuitable for sufacemountng

Low DC Resistance , High Current high relabty.

Excellent In Solderability And Heat Resistance.

Operating Temp: -40 ~+125

◆Application

High frequency line of communication equipment and wireless module
Bluetooth,Audio Circuit.

Other Electronic Equipment.

◆Part Number

FQW	2B	AN	2N7	J	0	L
①	②	③	④	⑤	⑥	⑦

①Product Typel:

FQW: Wire Wound Inductor Series

②Dimensions: 0805(2.0×1.2mm)

③Material Code: C / A---Ferrite core

④Inductance: 010=10nH、R10=100nH、1R0=1.0μH、100=10μH ⑤

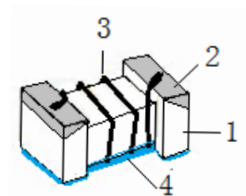
Tolerance: G ---±2%; J---±5%; K---±10%; M---±20%

⑥Electrode specification:

⑦Packaging D:paoer taping *B: bulk *L:embossed taping

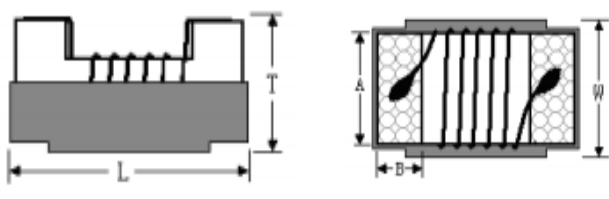
- 1.Core
- 2.Electrode
- 3.Wire
- 4.Encapsulation Layer

◆ Product



Externaldimensions

Unit : mm (inch)

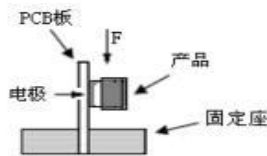


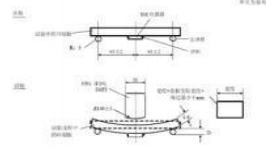
Size	L (Max)	W (Max)	T (Max)	A	B
2012 (0805)	2.30 (0.091)	1.70 (0.067)	1.52 (0.060)	1.27 (0.050)	0.50 (0.020)

ElectricalProperties:

Part NO	Inductance (nH)	Tolerance	Q (Min)	SRF (MHz) Min	Rdc (Ω) Max	Idc(mA) Max
FQW2BAN2N7J0L	2.7@250MHz	±5%	50@1500MHz	8000	0.045	800
FQW2BAN5N1J0L	5.6@250MHz	±5%	50@1000MHz	5500	0.065	600
FQW2BAN6N8J0L	6.8@250MHz	±5%	50@1000MHz	5500	0.110	600
FQW2BAN8N2J0L	8.2@250MHz	±5%	35@1000MHz	4700	0.200	600
FQW2BAN10NJ0L	10@250MHz	±5%	50@500MHz	4200	0.150	600
FQW2BAN12NJ0L	12@250MHz	±5%	50@500MHz	4000	0.150	600
FQW2BAN15NJ0L	15@250MHz	±5%	45@500MHz	3400	0.170	600
FQW2BAH18NJ0L	18@250MHz	±5%	55@500MHz	3300	0.200	600
FQW2BAN22NJ0L	22@250MHz	±5%	55@500MHz	2600	0.220	500
FQW2BAH27NJ0L	27@250MHz	±5%	55@500MHz	2500	0.250	500
FQW2BAN33NJ0L	33@250MHz	±5%	55@500MHz	2050	0.270	500
FQW2BAN39NJ0L	39@250MHz	±5%	55@500MHz	2000	0.290	500
FQW2BAN47NJ0L	47@200MHz	±5%	55@500MHz	1650	0.310	500
FQW2BAN56NJ0L	56@200MHz	±5%	55@500MHz	1550	0.340	500
FQW2BAH68NJ0L	68@200MHz	±5%	55@500MHz	1450	0.380	500
FQW2BAN75NJ0L	75@200MHz	±5%	55@500MHz	1400	0.400	400
FQW2BAN82NJ0L	82@150MHz	±5%	55@500MHz	1300	0.420	400
FQW2BAN10NJ0L	100@150MHz	±5%	50@500MHz	1200	0.460	400
FQW2BANR12J0L	120@150MHz	±5%	45@250MHz	1100	0.510	400
FQW2BANR15J0L	150@100MHz	±5%	45@250MHz	920	0.560	400
FQW2BANR18J0L	180@100MHz	±5%	45@250MHz	870	0.640	400
FQW2BANR22J0L	220@100MHz	±5%	40@250MHz	850	1.050	400
FQW2BANR27J0L	270@100MHz	±5%	40@250MHz	650	1.100	350
FQW2BANR33J0L	330@100MHz	±5%	40@250MHz	600	1.400	310
FQW2BANR39J0L	390@100MHz	±5%	40@250MHz	560	1.500	290
FQW2BANR47J0L	470@50MHz	±5%	33@100MHz	375	2.000	250
FQW2BANR56J0L	560@25MHz	±5%	23@50MHz	340	1.900	230
FQW2BANR68J0L	680@25MHz	±5%	23@50MHz	300	2.100	190
FQW2BANR75J0L	750@25MHz	±5%	23@50MHz	280	2.120	180
FQW2BANR82J0L	820@25MHz	±5%	23@50MHz	250	2.140	180
FQW2BANR91J0L	910@25MHz	±5%	20@50MHz	220	2.280	180
FQW2BAN1R0J0L	1000@25MHz	±5%	20@50MHz	200	2.400	170
FQW2BAN1R2J0L	1200@7.9MHz	±5%	18@50MHz	180	2.550	170
FQW2BAN1R5J0L	1500@7.9MHz	±5%	18@50MHz	170	2.800	160
FQW2BAN1R8J0L	1800@7.9MHz	±5%	18@50MHz	140	3.800	150
FQW2BAN2R2J0L	2200@7.9MHz	±5%	16@7.9MHz	50	4.200	150

Reliability Test Method

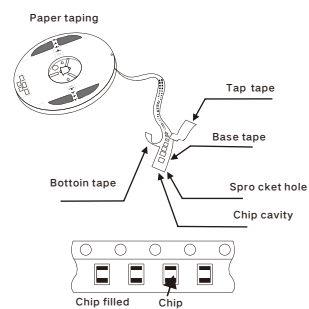
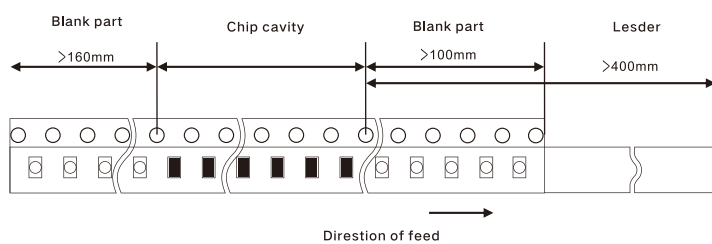
No.	Items	Requirements	Test Methods and Remarks										
1	Solder ability	No visible mechanical damage. Electrode surface solder coverage. FHW-UC/HC series: $\geq 80\%$.	Dip pads in flux and dip in solder pot(96.5Sn/3.0Ag/0.5Cu)at $245\pm 3^{\circ}\text{C}$ for $3\pm 0.3\text{s}$.										
2	Resistance to Soldering	No visible mechanical damage. ②Inductance shall not change more than $\pm 5\%$; ③Q shall not change more than $\pm 10\%$.	(96.5%Sn/3.0%Ag/0.5%Cu) $10\pm 1\text{s}$ 。 Dippadsin flux and dip in solder pot(96.5Sn/3.0Ag/0.5Cu)at $260\pm 5^{\circ}\text{C}$ for $10\pm 1\text{s}$.										
3	Vibration	①No visible mechanical damage. ②Inductance shall not change more than $\pm 5\%$; ③Q shall notchange more than $\pm 10\%$.	Inductors shall be subjected to vibration of 1.5mm amplitude frequency 10~55Hz (10Hz to 55Hz to 10Hz in a period of 1 minute) for 2h in each of three(X、Y、Z) axes.										
4	Adhesion of electrode	①The end electrode did not fall off after the test. ②No visible mechanical damage.	Weld the product on the PCB board, and apply force as shown in the diagram, direction and requirement.										
													
			<table><tr><td>Size</td><td></td></tr><tr><td>0402IF Series</td><td>3 N</td></tr><tr><td>0603PF/IF Series</td><td>7 N</td></tr><tr><td colspan="2">Keep time: (10±1)s</td></tr><tr><td colspan="2">Speed: 1.0 mm/s.</td></tr></table>	Size		0402IF Series	3 N	0603PF/IF Series	7 N	Keep time: (10±1)s		Speed: 1.0 mm/s.	
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5	Low temperature resistance	① No visible mechanical damage. ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$.	① FHD-PF/IF series shall be subjected to $-40\pm 2^{\circ}\text{C}$ for 1000 +24 -0 h
6	High temperature resistance	① No visible mechanical damage. ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$.	① FHD-PF/IF series shall be subjected to $+85\pm 5^{\circ}\text{C}$ for 1000 +24 -0 h
7	Temperature Shock	① No visible mechanical damage. ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$.	① FHD-PF/IF series : $+85^{\circ}\text{C}$ 30minutes $\longleftrightarrow$ -40°C 30minutes 100 Cycles.
8	High temperature load	① No visible mechanical damage . ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$.	① FHD-PF/IF series shall be store at $85\pm 2^{\circ}\text{C}$ for 1000 — 0 h with rated current applied.
9	Static Humidity	① No visible mechanical damage. ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$.	Inductors shall be subjected to 90%~95%RH. at $60\pm 2^{\circ}\text{C}$ for 1000 +24 — 0 h
10	Beding strength	No visible mechanical damage.	① Install the inductor on the test substrate; Apply force in the vertical direction (as shown below). ② The epoxy plate should bend down to (2 ± 0.2) mm at the bending rate of (1 ± 0.5) mm/s , Keep time (20 ± 1) sec.
			
11	Solvent Resistance	① No visible mechanical damage. ② Inductance shall not change more than $\pm 5\%$; ③ Q shall not change more than $\pm 10\%$	Soak in the element $23\pm 5^{\circ}\text{C}$ in isopropyl alcohol solution, keep 5 ± 0.5 min.

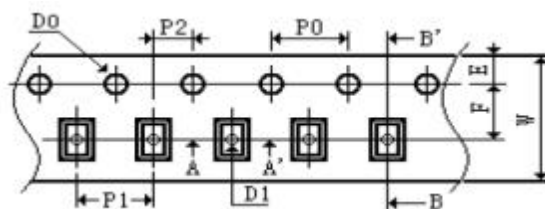
*Taping dimensions (Unit: mm)

*Leader and blank portion

◆Packaging



Paper tape



Part NO.	W	E	F	D0	D1	P0	P1	P2	P0×10
(2012) 0805	8.00	1.75	3.50	1.55	0.65	4	4	2	40